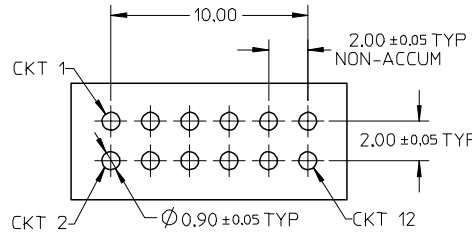
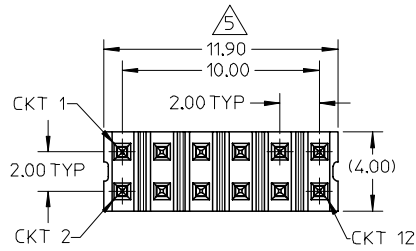
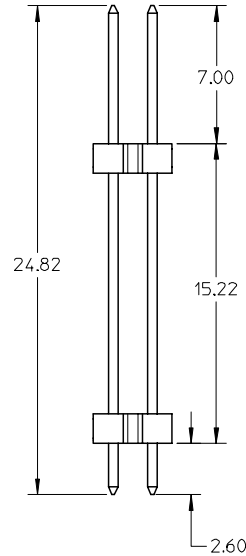
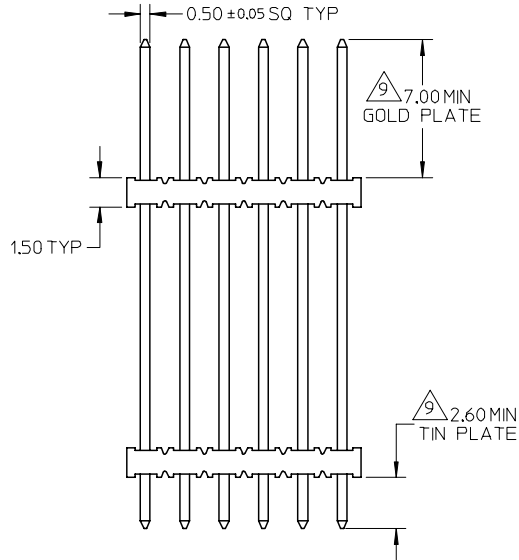


10 9 8 7 6 5 4 3 2 1

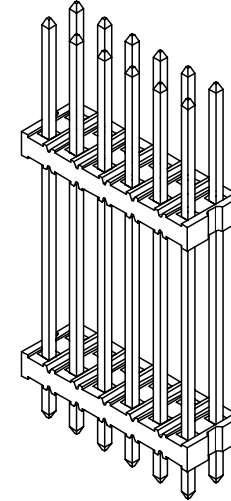


PCB LAYOUT: COMPONENT SIDE
RECOMMENDED PCB THICKNESS: 1.60 ± 0.10mm



NOTES:

1. MATERIAL:
HSG: NYLON, GLASS-FILLED, UL94V-0 COLOR: BLACK
PIN: 0.50MM SQ, COPPER ALLOY
2. PLATING FINISH:
0.762µm MIN. GOLD PLATE ON CONTACT AND
1.905µm MIN. TIN ON SOLDER TAIL OVER
1.270µm MIN. NICKEL OVERALL.
3. PIN PUSHOUT FORCE: 0.85KgF MIN IN EITHER DIRECTION.
4. WAFER TO BE FLAT WITHIN 0.003 mm/mm
5. IRREGULAR CIRCUIT CUTOFF WITHIN BREAKAWAY SECTION IS PERMISSIBLE. CUTTING OR CHIPPING OF THE MAIN BODY IS NOT ACCEPTABLE
6. PART TO BE PACKED IN TRAY
7. PRODUCT SPECIFICATION: PS-87761-100
8. PACKAGING SPECIFICATION: PK-89990-487
9. ASSEMBLE GOLD & TIN PLATE END AS SHOWN



NEW RELEASED EC NO: S2007-0475 DRWN: SKLIM01 CHKD: CWLAM APPR: KWLEE	2007/01/03 2007/01/04 2007/01/05	DESCRIPTION REV	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
			▼=0 ▽=0	mm INCH	MM ONLY	NTS	METRIC	
				4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.20 ± --- 1 PLACE ± --- ± ---	DRAWN BY DATE SKLIM01 2006/12/15 CHECKED BY DATE CWLAM 2007/01/03 APPROVED BY DATE KWLEE 2007/01/03	TITLE	CUSTOM HEADER M-GRID, DUAL WAFER HEADER, VERTICAL T/H	
				ANGULAR ± 3 °	MATERIAL NO. 87761-1201	mox DOCUMENT NO. SD-87761-058	SHEET NO. 1 OF 1	

9 8 7 6 5 4 3 2 1